

RN SERIES THIN FILM RESISTOR



RN04

Total Wt. Mg 0.7

PART STRUCTURE	SUBPART WT. MG.	MATERIAL	MATERIAL %	MATERIAL WT. MG.
Ceramic Substrate	.567	A1203 721308-30-1	96%	0.544
		SiO2 15468-32-3	2%	0.011
		MgO 109170-28-7	2%	0.011
Conductor Layer (Bottom)	0.0035	Ag 13967-01-6	100%	0.0035
Conductor Layer (Top)	0.00009	Cu 7440-50-8	80%	0.000072
		Ti 14304-90-6	5%	0.000004
		W 7440-33-7	15%	0.000013
Resistive Element	0.0028	Cr 7440-47-3	45%	0.0012
		Ni 7440-02-0	50%	0.0014
		Si 53170-73-3	5%	0.00014
Over-Coating	0.0672	Epoxy N/A	100%	0.0672
Marking	0.0011	Epoxy N/A	99%	0.00108
		Ba 1214-39-7	1%	0.000011
C2	0.00084	Cr 7440-47-3	20%	0.00016
		Ni 7440-02-0	80%	0.000672
Ni Plating	0.0299	Ni 7440-02-0	100%	0.0299
Sn Plating	0.0266	Sn 7440-31-5	100%	0.0266



RN06

Total Wt. Mg 2.05

PART STRUCTURE	SUBPART WT. MG.	MATERIAL	MATERIAL %	MATERIAL WT. MG.
Ceramic Substrate	1.6617	A12O3 721308-30-1	96%	1.595232
		SiO2 15468-32-3	2%	0.033234
		MgO 109170-28-7	2%	0.033234
Conductor Layer (Bottom)	0.0105	Ag 139670-01-6	100%	0.0105
Conductor Layer (Top)	0.003	Cu 7440-50-8	80%	0.00024
		Ti 14304-90-6	5%	0.000015
		W 7440-33-7	15%	0.000045
Resistive Element	0.0084	Cr 7440-47-3	45%	0.00378
		Ni 7440-02-0	50%	0.0042
		Si 53170-73-3	5%	0.00042
Over-Coating	0.1964	Epoxy N/A	100%	0.1964
Marking	0.0032	Epoxy N/A	99%	0.003168
		Ba 1214-39-7	1%	0.000032
C2	0.0025	Cr 7440-47-3	20%	0.0005
		Ni 7440-02-0	80%	0.002
Ni Plating	0.0877	Ni 7440-02-0	100%	0.0877
Sn Plating	0.0783	Sn 7440-31-5	100%	0.0783



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 RN10
Total Wt. Mg 4.0

PART STRUCTURE	SUBPART WT. MG.	MATERIAL CAS	MATERIAL %	SUBPART WT. MG.
Ceramic Substrate	3.240	A12O3 721308-30-1	96%	3.1104
		SiO2 15468-32-3	2%	0.0648
		MgO 109170-28-7	2%	0.0648
Conductor Layer (Bottom)	0.0204	Ag 139670-01-6	100%	0.0204
Conductor Layer (Top)	0.00584	Cu 7440-50-8	80%	0.004672
		Ti 14304-90-6	5%	0.000292
		W 7440-33-7	15%	0.000876
Resistive Element	0.016	Cr 7440-47-3	45%	0.0072
		Ni 7440-02-0	50%	0.008
		Si 53170-73-3	5%	0.0008
Over-Coating	0.384	Epoxy N/A	100%	0.384
Marking	0.0063	Epoxy N/A	99%	0.006237
		Ba 1214-39-7	1%	0.000063
C2	0.0049	Cr 7440-47-3	20%	0.00098
		Ni 7440-02-0	80%	0.00392
Ni Plating	0.1736	Ni 7440-02-0	100%	0.1736
Sn Plating	0.1493	Sn 7440-31-5	100%	0.1493

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RN12

Total Wt. Mg 7.5

PART STRUCTURE	SUBPART WT. MG.	MATERIAL	MATERIAL %	MATERIAL WT. MG.
Ceramic Substrate	6.075	A12O3 721308-30-1	96%	5.832
		SiO2 15468-32-3	2%	0.1215
		MgO 109170-28-7	2%	0.1215
Conductor Layer (Bottom)	0.03825	Ag 139670-01-6	100%	0.03825
Conductor Layer (Top)	0.01095	Cu 7440-50-8	80%	0.00876
		Ti 14304-90-6	5%	0.0005475
		W 7440-33-7	15%	0.0016425
Resistive Element	0.030	Cr 7440-47-3	45%	0.0135
		Ni 7440-02-0	50%	0.015
		Si 53170-73-3	5%	0.0015
Over-Coating	0.72	Epoxy N/A	100%	0.72
Marking	0.0118	Epoxy N/A	99%	0.011682
		Ba 1214-39-7	1%	0.000118
C2	0.00919	Cr 7440-47-3	20%	0.001838
		Ni 7440-02-0	80%	0.007352
Ni Plating	0.3255	Ni 7440-02-0	100%	0.3255
Sn Plating	0.280	Sn 7440-31-5	100%	0.280

